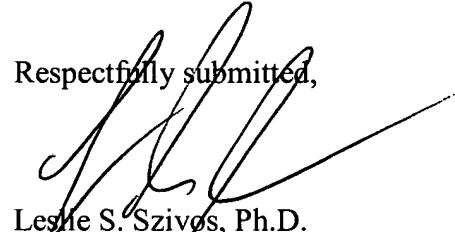


REMARKS

Favorable consideration and allowance of the claims of the present application, as presently filed, are respectfully requested.

In this preliminary amendment, applicants have canceled original Claims 1-56, added new Claims 60-62 and have amended the specification to include information regarding the parent application. Claims 1-52 are the subject matter of parent application U.S. Serial No. 09/706,492 filed November 3, 2000. Claims 53-56 are the subject matter of the divisional application U.S. Serial No. 09/862,827 filed on May 22, 2001. Newly added Claim 60 clearly recites that the identical material of the wordline and local interconnect is a W/WN stack. Support for this newly added claim is found of Page 14, lines 20-22, of applicants' specification. Newly added Claim 61 recites that the identical material of the wordline and the local interconnect can further include a SiN cap. Support for this newly added claim is found on Page 14, lines 20-22, of applicants' specification. Newly added Claim 62 recites that the wordline and interconnect are identically layered, where the top surfaces of the layer are approximately co-planar. Support for this claim is found on Page 14, lines 20-30, and Page 19, lines 23-29, of applicants' specification, where applicants disclose that the interconnect and wordline comprise the same material formed by depositing a W/WN or other metal layer and then patterning the layer. Therefore, since the interconnect and wordline are formed from the same material layer, and at the same time the surfaces of the layers are approximately co-planar.

Wherefore, consideration and allowance of the claims of the present application
are respectfully requested.

Respectfully submitted,

Leslie S. Szivos, Ph.D.
Registration No. 39,394

Scully, Scott, Murphy & Presser
400 Garden City Plaza
Garden City, New York 11530
(516) 742-4343
LSS:HAH:kc